



## Customer Information Notification

2021090111 : LPC804M101JHI33 Marking Format Update to Add Wafer Fab Code

**Note:** This notice is NXP Company Proprietary.

**Issue Date:** Sep 29, 2021 **Effective date:** Sep 30, 2021

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### Management summary

The LPC804M101JHI33 marking format will be updated to add a wafer fab code.

### Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input checked="" type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

## PCN Overview

### Description

The LPC804M101JHI33 marking format will be updated to add wafer fab code. The effective date code will be 2140.

A wafer fab code character is added to the beginning of the last line of the top side marking. "Z" stands for the current wafer fab, SSMC.

A new datasheet has been issued with updated marking information.

[https://www.nxp.com/docs/en/nxp/data-sheets/LPC804\\_DS.pdf](https://www.nxp.com/docs/en/nxp/data-sheets/LPC804_DS.pdf).

### Reason

To provide traceability for multiple fab sourcing.

### Identification of Affected Products

Top Side Marking

A wafer fab code character is added to the beginning of the last line of the top side marking. "Z" stands for the current wafer fab, SSMC. See attached marking description.

### Anticipated Impact on Form, Fit, Function, Reliability or Quality

### Data Sheet Revision

A new datasheet will be issued

### Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
LPC804M101JHI33Y	935346816518	LPC804M101JHI33	32-bit ARM Cortex-M0+	H(V)QFN32	SOT617-11	RFS	No	BLM1
LPC804M101JHI33E	935346816551	LPC804M101JHI33	32-bit ARM Cortex-M0+	H(V)QFN32	SOT617-11	RFS	No	BLM1